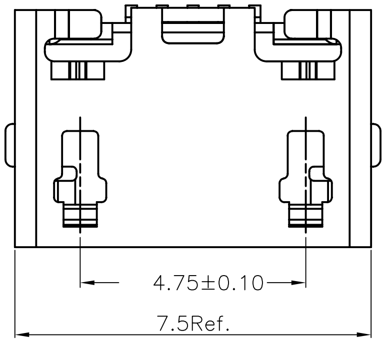
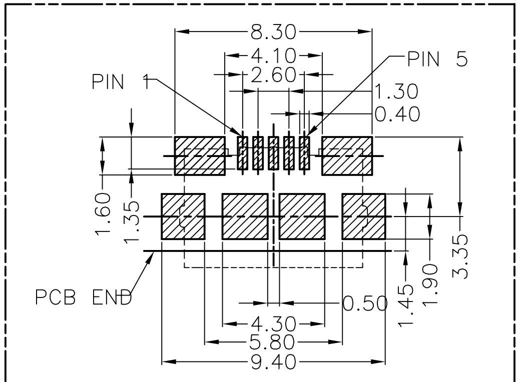
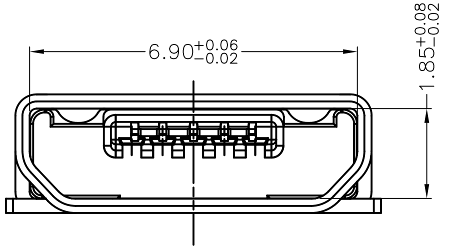
THE PART MEETS TECONN "GP001" COMPLIANCE

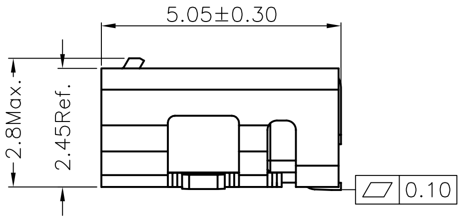


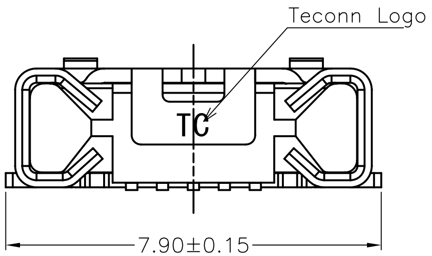


REFERANCE PCB LAYOUT(TOP VIEW)

SCALE 1:2(TOLERANCE:±0.05)





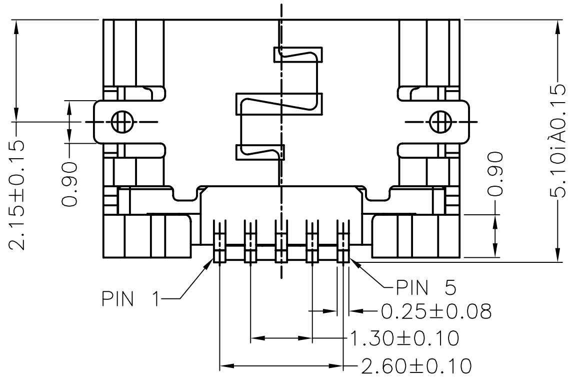


A4A0502-X-XX-R

LOGO — Mating Area plating

E: With "TC" LOGO
F: Without LOGO

01: Au 1u"Min.
03: Au 3u"Min.
05: Au 5u"Min.
10: Au 10u"Min.
15: Au 15u"Min.
30: Au 30u"Min.



1.Contact Resistance:30mOHM Max.;

2.Dielectric Withstanding Voltage:100V AC For 1 Minute;

3.Insulation Resistance:1000M OHM Min.;

4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;

5.Durability:10000 Cycles;

Item	Title	Material	Dispose
1	Shell	Stainless Steel	Matte Tin 80u"min.
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails::G/F.
3	InsertMolding	LCP	UL94V-0

X.	±	0.35
.X	±	0.25
.XX	±	0.15
.XXX±		
X°	±	2°
.X°	±	1.5°

APPD: Henry Sun

CHKD:

DR: Kevin Han

TITLE: MICRO USB B/F 5PIN SMT

PART NO: A4A0502-E(F)-XX-R

泰康电子
TECONN

UNITS: mm

SCALE: 1:1

DWG NO: C-A4A0502-E(F)-XX-R

CUSTOMER DRAWING

SHEET:1OF1

REV: A

REV	ECN NO	DESCRIPTION	DATE
A	TE2013-0512	New Drawing	2013/11/23